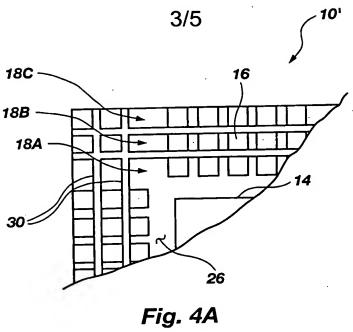


QUAD FLAT NO-LEAD (QFN) GRID ARRAY PACKAGE, METHOD OF MAKING AND MEMORY MODULE AND COMPUTER SYSTEM SIGNATURE.

Inventors: Setho Sing Fee et al. Filed: December 5, 2003 Attorney Docket No. 4738.1US



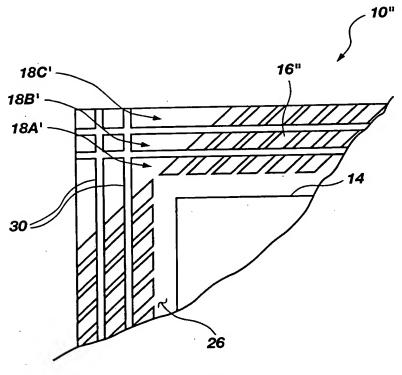


Fig. 4B

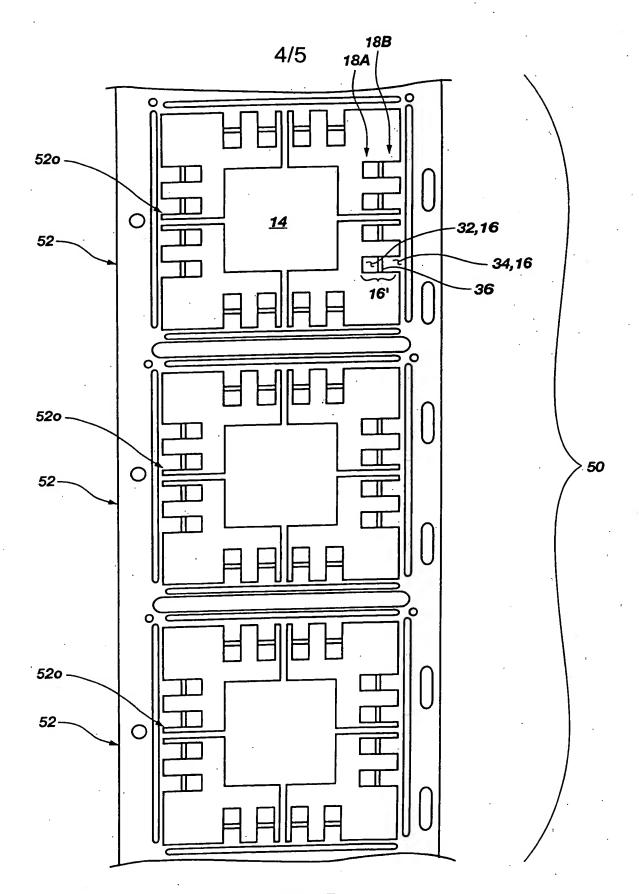


Fig. 5

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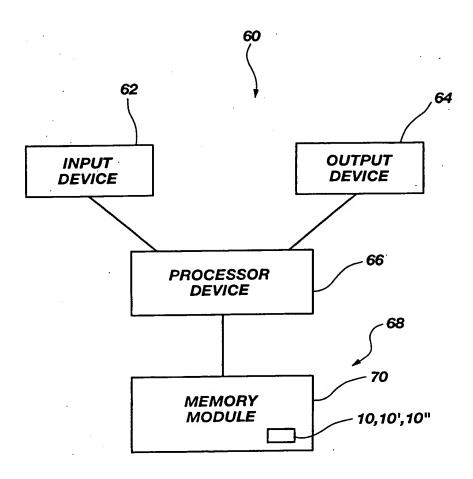


Fig. 6